



# Q NOTE

Q NOTE	Revision	Date	Sheet
CX	1	8/20/13	1 of 1

**Revisions:**

Rev	Originator / Date	Revised / Date	Approval / Date:	Description:
1	RPS / 8/20/13		REH 8/28/13	Originated

## SOLDERING REQUIREMENTS (IPC J-STD-001E)

IPC J-STD-001E, Class 3 (Requirements for Soldering Electrical and Electronic Assemblies) with the modifications listed below is a requirement of this purchase order.

**Note:** This Quality Note is NOT intended to apply to Component Parts or Component Assemblies subject to soldering at a higher level of assembly where reflow could take place. It is understood that High Temperature Solders are appropriate and required to prevent solder reflow at a higher level of assembly.

a. Solder alloys, such as Sn60Pb40, Sn62Pb36Ag2, and Sn63Pb37, shall be in accordance with J-STD-006. Other solder alloys **shall not** be used for electrical and electronic assembly soldering unless otherwise specified on the drawing or purchase order. (Reference J-STD-001E Para. 3.2)

b. Process Validation and control cannot be substituted for 100% X-Ray inspection of Ball Grid Arrays (BGAs) and Bottom Terminated Components (BTCs) unless it is part of a documented process control program agreed to by the Caton Connector procuring agency. (Reference J-STD-001E Para. 7.5.14 and 7.5.15).

c. When NiPdAu (nickel / palladium / gold) is used as a surface finish where the gold is applied either through electroless or electrolytic processes resulting in over 8 micro inches of gold, there shall be objective evidence, available for review, that there are no gold related solder embrittlement issues. (Reference IPC J-STD-001E, Paragraph 4.5).

Compliance to the requirements of this standard is subject to Caton Connector review at any time during the performance of this order.

This document is an integral part of the contract (purchase order), which calls it out. The revision in effect at the time the purchase order was placed applies.
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